

FCH47N60N

N-Channel MOSFET

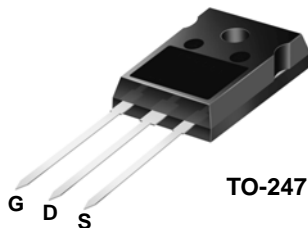
600V, 47A, 62mΩ

Features

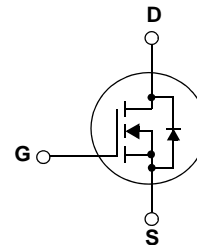
- 650V @T_J = 150°C
- R_{DS(on)} = 51.5mΩ (Typ.)@ V_{GS} = 10V, I_D = 23.5 A
- Ultra Low Gate Charge (Typ. Q_g = 115nC)
- Low Effective Output Capacitance
- 100% Avalanche Tested
- RoHS Compliant

Description

The SupreMOS MOSFET, Fairchild's next generation of high voltage super-junction MOSFETs, employs a deep trench filling process that differentiates it from preceding multi-epi based technologies. By utilizing this advanced technology and precise process control, SupreMOS provides world class R_{sp}, superior switching performance and ruggedness. This SupreMOS MOSFET fits the industry's AC-DC SMPS requirements for PFC, server/telecom power, FPD TV power, ATX power, and industrial power applications.



TO-247



MOSFET Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter	Ratings	Units
V _{DSS}	Drain to Source Voltage	600	V
V _{GSS}	Gate to Source Voltage	±30	V
I _D	Drain Current	-Continuous (T _C = 25°C)	47
		-Continuous (T _C = 100°C)	29.7
I _{DM}	Drain Current	- Pulsed (Note 1)	141
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	3068
I _{AR}	Avalanche Current		15.7
E _{AR}	Repetitive Avalanche Energy		3.7
dv/dt	MOSFET dv/dt Ruggedness		100
	Peak Diode Recovery dv/dt	(Note 3)	20
P _D	Power Dissipation	(T _C = 25°C)	368
		- Derate above 25°C	2.94
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to +150	°C
T _L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds	300	°C

*Drain current limited by maximum junction temperature

Thermal Characteristics

Symbol	Parameter	Ratings	Units
R _{θJC}	Thermal Resistance, Junction to Case	0.34	°C/W
R _{θCS}	Thermal Resistance, Case to Heat Sink (Typical)	0.24	
R _{θJA}	Thermal Resistance, Junction to Ambient	40	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FCH47N60N	FCH47N60N	TO-247	-	-	30

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
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Off Characteristics

BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 1\text{mA}, V_{GS} = 0\text{V}, T_C = 25^\circ\text{C}$	600	-	-	V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 1\text{mA}$, Referenced to 25°C	-	0.78	-	$\text{V}/^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 480\text{V}, V_{GS} = 0\text{V}$ $V_{DS} = 480\text{V}, V_{GS} = 0\text{V}, T_C = 125^\circ\text{C}$	-	-	10 100	μA
I_{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 30\text{V}, V_{DS} = 0\text{V}$	-	-	± 100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250\mu\text{A}$	2	-	4	V
$R_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{V}, I_D = 23.5\text{A}$		51.5	62.0	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{DS} = 40\text{V}, I_D = 23.5\text{A}$		56		S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 100\text{V}, V_{GS} = 0\text{V}$ $f = 1\text{MHz}$	-	5037	6700	pF
C_{oss}	Output Capacitance		-	200	270	pF
C_{riss}	Reverse Transfer Capacitance		-	2.5	4.0	pF
C_{oss}	Output Capacitance	$V_{DS} = 380\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$	-	108		pF
$C_{oss,eff.}$	Effective Output Capacitance	$V_{DS} = 0\text{V to } 380\text{V}, V_{GS} = 0\text{V}$	-	511		pF
$Q_{g(tot)}$	Total Gate Charge at 10V	$V_{DS} = 380\text{V}, I_D = 23.5\text{A},$ $V_{GS} = 10\text{V}$ (Note 4)	-	115	151	nC
Q_{gs}	Gate to Source Gate Charge		-	21		nC
Q_{gd}	Gate to Drain "Miller" Charge		-	34		nC
ESR	Equivalent Series Resistance(G-S)	Drain Open	-	0.9		Ω

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 380\text{V}, I_D = 23.5\text{A}$ $R_{GEN} = 4.7\Omega$ (Note 4)	-	11	32	ns
t_r	Turn-On Rise Time		-	9	28	ns
$t_{d(off)}$	Turn-Off Delay Time		-	135	280	ns
t_f	Turn-Off Fall Time		-	22	54	ns

Drain-Source Diode Characteristics

I_S	Maximum Continuous Drain to Source Diode Forward Current	-	-	47	A	
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	141	A	
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{V}, I_{SD} = 23.5\text{A}$	-	-	1.2	V
t_{rr}	Reverse Recovery Time	$V_{GS} = 0\text{V}, I_{SD} = 23.5\text{A}$	-	495	-	ns
Q_{rr}	Reverse Recovery Charge	$di_F/dt = 100\text{A}/\mu\text{s}$	-	12	-	μC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. $I_{AS} = 15.7\text{A}$, $R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq 47\text{A}$, $di/dt \leq 200\text{A}/\mu\text{s}$, $V_{DD} \leq 380\text{V}$, Starting $T_J = 25^\circ\text{C}$
4. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

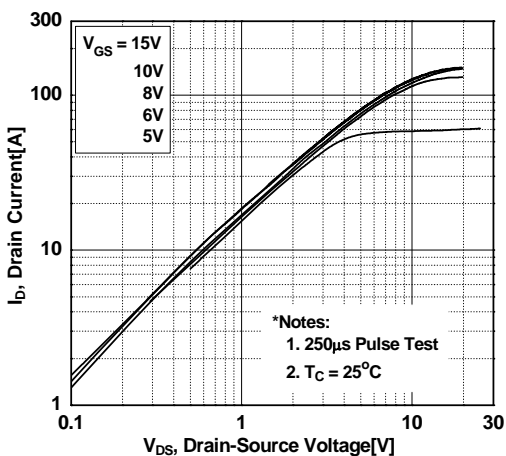


Figure 2. Transfer Characteristics

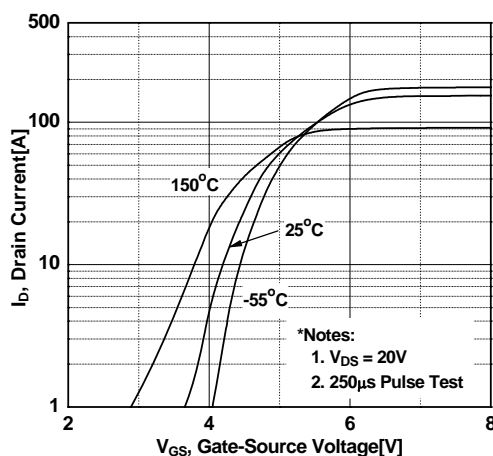


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

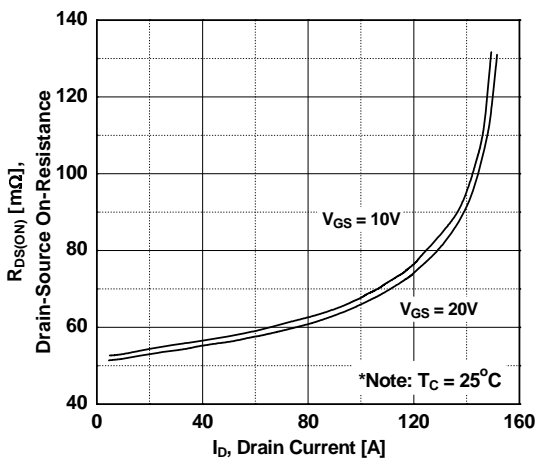


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

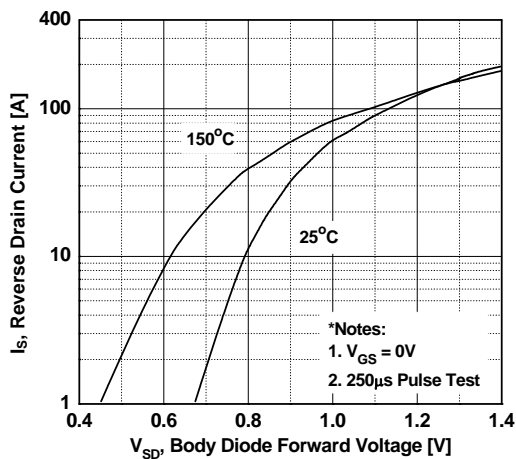


Figure 5. Capacitance Characteristics

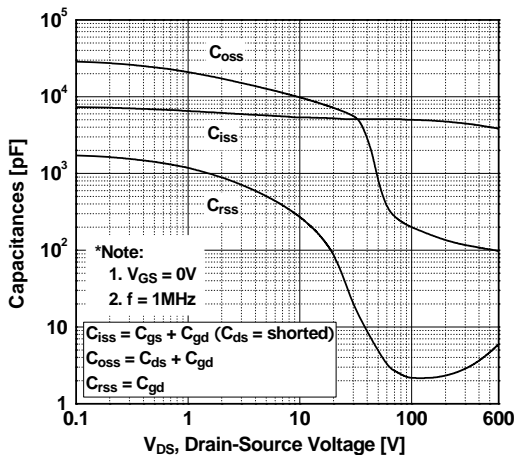
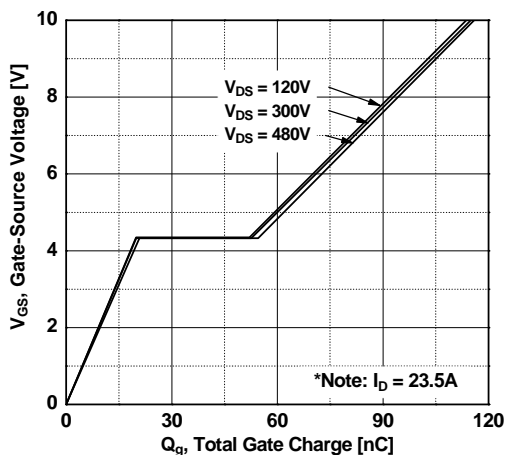


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

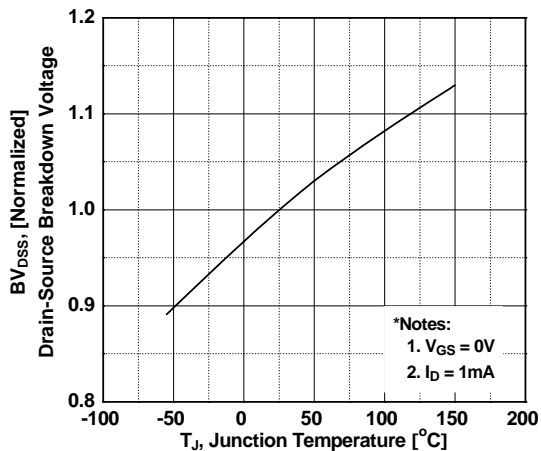


Figure 8. On-Resistance Variation vs. Temperature

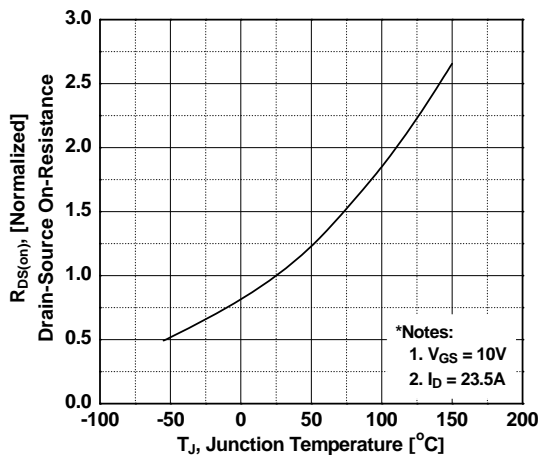


Figure 9. Maximum Safe Operating Area

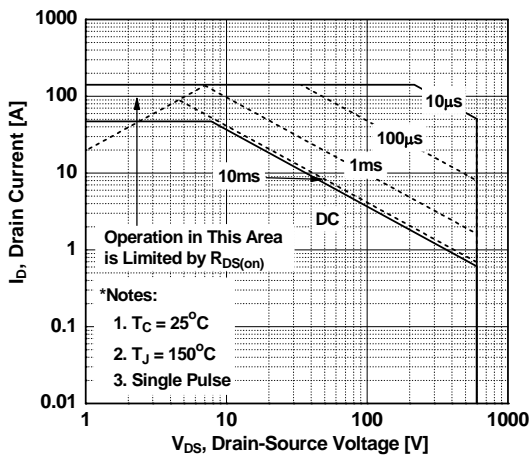


Figure 10. Maximum Drain Current vs. Case Temperature

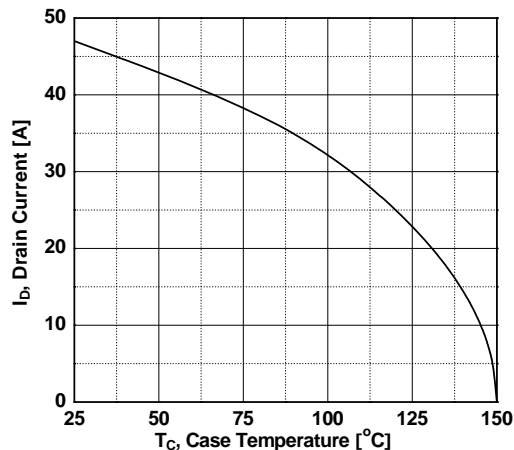
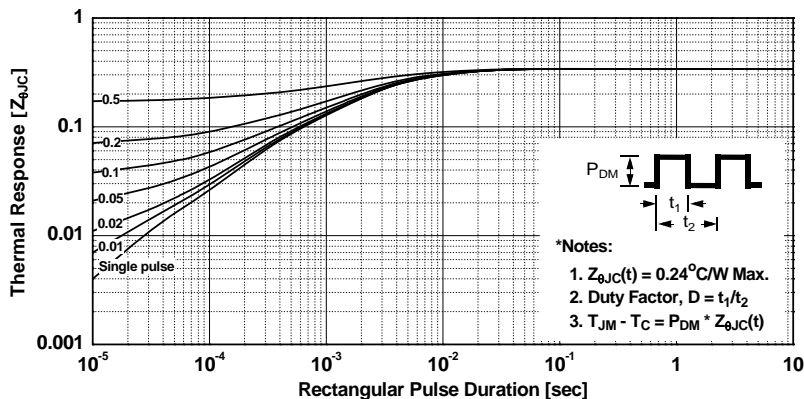
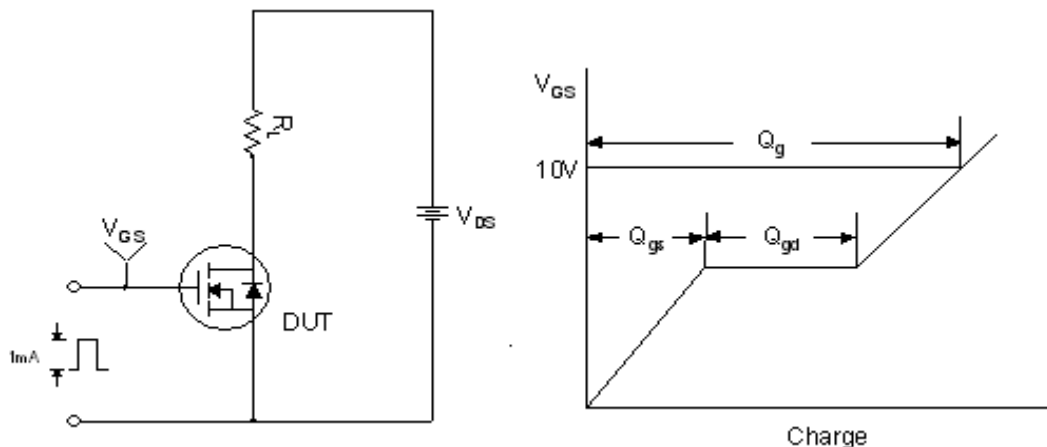


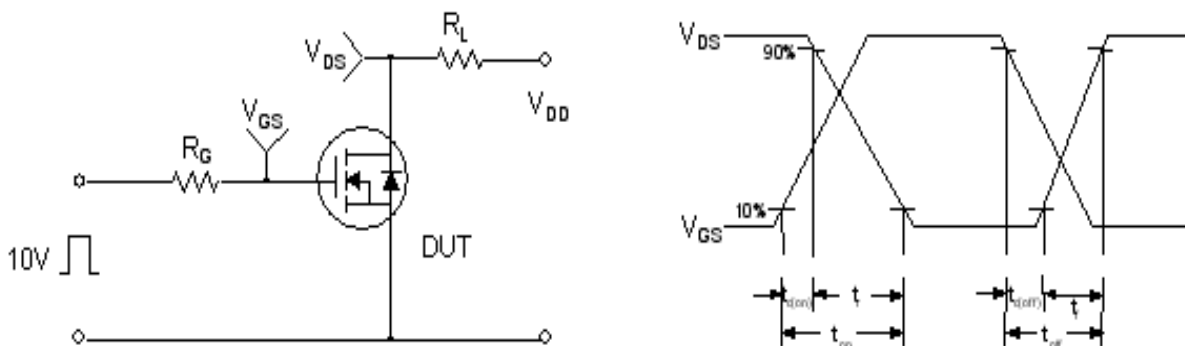
Figure 11. Transient Thermal Response Curve



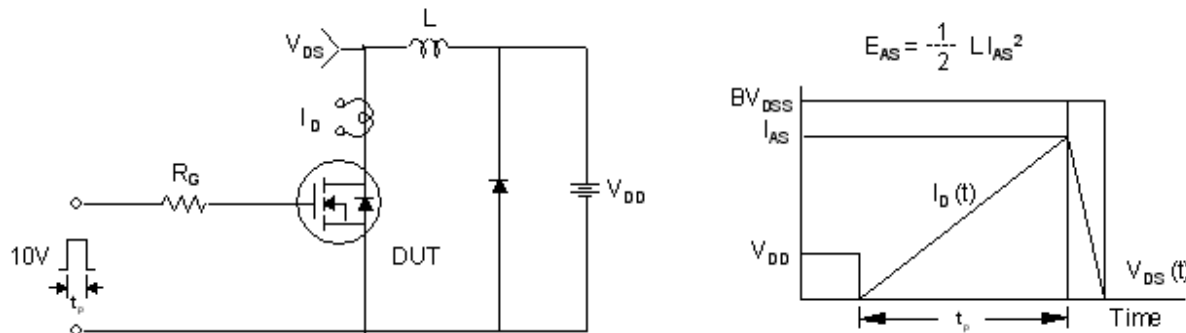
Gate Charge Test Circuit & Waveform



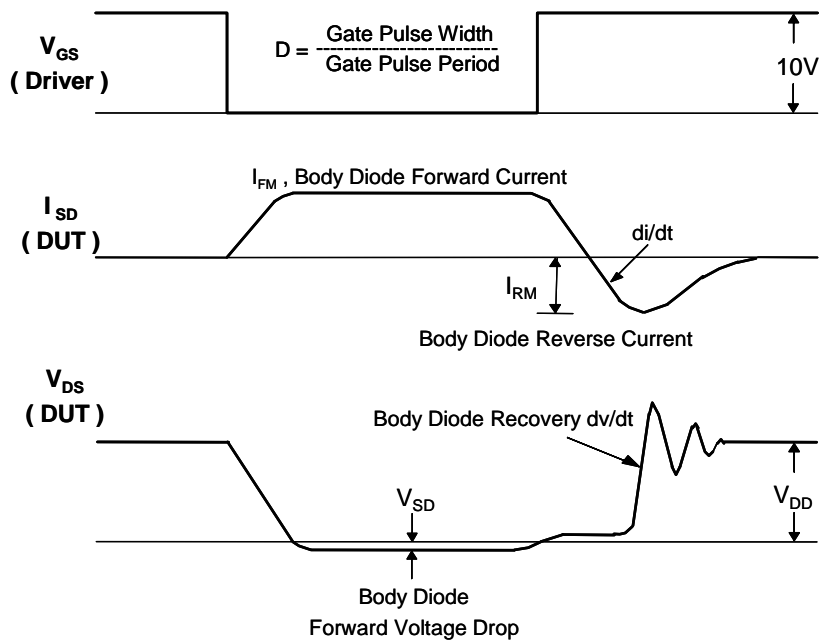
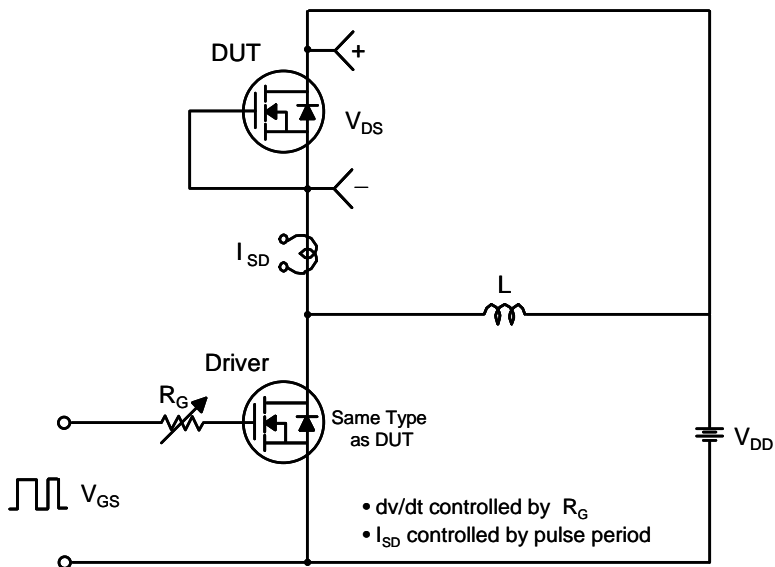
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

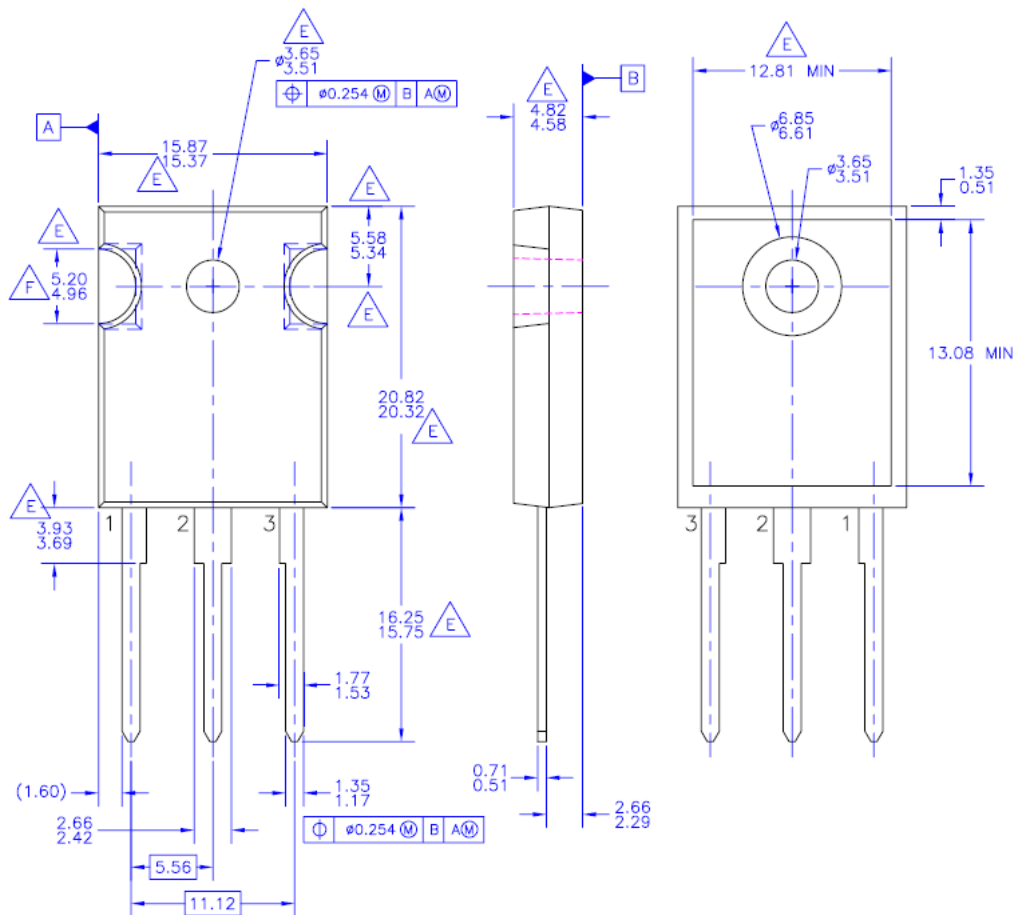


Peak Diode Recovery dv/dt Test Circuit & Waveforms



Mechanical Dimensions

TO-247



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